

**Notice of References Cited**

Application/Control No.

10/026,125

Applicant(s)/Patent Under  
Reexamination  
CHOU ET AL.

Examiner

Evan Pert

Art Unit

2829

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-			
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	D	US-			
	E	US-			
	F	US-			
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	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

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**NON-PATENT DOCUMENTS**

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	X	

\*A copy of this reference is not being furnished with this Office action (See MPEP § 707.05(a))  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign